

ABSTRACT:

The invention relates to a method of forming electrical connection means on a substrate, which method comprises the following steps:

- a) depositing an intermediate layer of material (14) on a substrate (10),
- b) forming an etching mask having at least one window,
- 5 c) etching the layer of intermediate material in conformity with the mask in order to form at least one aperture therein,
- d) coating the lateral side-walls of the aperture with a spacer (22) in order to narrow the aperture,
- e) depositing at least one conductor material (24) so as to fill the narrowed
10 aperture, and
- f) performing an abrasion operation so as to remove excess conductor material outside the aperture.

The invention is used for the realization of wiring tracks, contact pads and
vias.

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Fig. 6